

FEATURES

Low Insertion Loss and On Resistance: 2.2 Ω Typical

On Resistance Flatness 0.5 Ω Typical

Automotive Temperature Range

-40°C to +125°C

-3 dB Bandwidth = 240 MHz

Single 3 V/5 V Supply Operation

Rail-to-Rail Operation

Very Low Distortion: 0.5%

Low Quiescent Supply Current (1 nA Typical)

Fast Switching Times

t_{ON} 7 ns

t_{OFF} 4 ns

TTL/CMOS Compatible

APPLICATIONS

USB 1.1 Signal Switching Circuits

Cell Phones

PDAs

Battery-Powered Systems

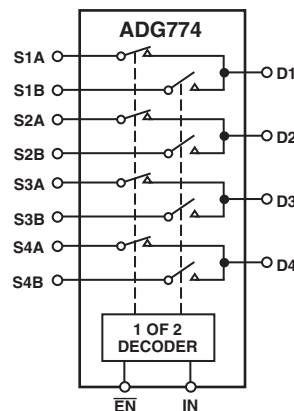
Communications Systems

Data Acquisition Systems

Token Ring 4 Mbps/16 Mbps

Audio and Video Switching

Relay Replacement

FUNCTIONAL BLOCK DIAGRAM

GENERAL DESCRIPTION

The ADG774 is a monolithic CMOS device comprising four 2:1 multiplexer/demultiplexers with high impedance outputs. The CMOS process provides low power dissipation yet gives high switching speed and low on resistance. The on resistance variation is typically less than 0.5 Ω with an input signal ranging from 0 V to 5 V.

The bandwidth of the ADG774 is greater than 200 MHz; this, coupled with low distortion (typically 0.5%), makes the part suitable for switching USB 1.1 data signals and fast Ethernet signals.

The on resistance profile is very flat over the full analog input range ensuring excellent linearity and low distortion when switching audio signals. Fast switching speed, coupled with high signal bandwidth, also makes the parts suitable for video signal switching. CMOS construction ensures ultralow power dissipation, making the parts ideally suited for portable and battery-powered instruments.

The ADG774 operates from a single 3.3 V/5 V supply and is TTL logic compatible. The control logic for each switch is shown in the Truth Table.

These switches conduct equally well in both directions when ON, and have an input signal range that extends to the supplies. In the OFF condition, signal levels up to the supplies are blocked. The ADG774 switches exhibit break-before-make switching action.

PRODUCT HIGHLIGHTS

1. Wide -3 dB Bandwidth, 240 MHz.
2. Ultralow Power Dissipation.
3. Extended Signal Range.
The ADG774 is fabricated on a CMOS process giving an increased signal range that fully extends to the supply rails.
4. Low Leakage Over Temperature.
5. Break-Before-Make Switching.
This prevents channel shorting when the switches are configured as a multiplexer.
6. Crosstalk Typically -70 dB @ 30 MHz.
7. Off Isolation Typically -60 dB @ 10 MHz.

REV. C

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ADG774* PRODUCT PAGE QUICK LINKS

Last Content Update: 02/23/2017

COMPARABLE PARTS

View a parametric search of comparable parts.

DOCUMENTATION

Application Notes

- AN-1024: How to Calculate the Settling Time and Sampling Rate of a Multiplexer

Data Sheet

- ADG774: CMOS 3 V/5 V, Wide Bandwidth Quad 2:1 Mux Data Sheet

REFERENCE MATERIALS

Product Selection Guide

- Switches and Multiplexers Product Selection Guide

Technical Articles

- CMOS Switches Offer High Performance in Low Power, Wideband Applications
- Data-acquisition system uses fault protection
- Enhanced Multiplexing for MEMS Optical Cross Connects
- Temperature monitor measures three thermal zones

DESIGN RESOURCES

- ADG774 Material Declaration
- PCN-PDN Information
- Quality And Reliability
- Symbols and Footprints

DISCUSSIONS

View all ADG774 EngineerZone Discussions.

SAMPLE AND BUY

Visit the product page to see pricing options.

TECHNICAL SUPPORT

Submit a technical question or find your regional support number.

DOCUMENT FEEDBACK

Submit feedback for this data sheet.

ADG774—SPECIFICATIONS

SINGLE SUPPLY ($V_{DD} = 5\text{ V} \pm 10\%$, $GND = 0\text{ V}$. All specifications T_{MIN} to T_{MAX} unless otherwise noted.)

Parameter	B Version ¹			Unit	Test Conditions/Comments
	+25°C	–40°C to +85°C	–40°C to +125°C		
ANALOG SWITCH					
Analog Signal Range			0 V to V _{DD}	V	V _D = 0 V to V _{DD} , I _S = –10 mA
On Resistance (R _{ON})	2.2	5	7	Ω typ Ω max	
On Resistance Match between Channels (ΔR _{ON})	0.15	0.5	0.5	Ω typ Ω max	
On Resistance Flatness (R _{FLAT(ON)})	0.5	1	1	Ω typ Ω max	V _D = 0 V to V _{DD} , I _S = –1 mA
LEAKAGE CURRENTS					
Source OFF Leakage I _S (OFF)	±0.01 ±0.5	±1	±1.5	nA typ nA max	V _D = 4.5 V, V _S = 1 V; V _D = 1 V, V _S = 4.5 V; Test Circuit 2
Drain OFF Leakage I _D (OFF)	±0.01 ±0.5	±1	±1.5	nA typ nA max	V _D = 4.5 V, V _S = 1 V; V _D = 1 V, V _S = 4.5 V; Test Circuit 2
Channel ON Leakage I _D , I _S (ON)	±0.01 ±0.5	±1	±1.5	nA typ nA max	V _D = V _S = 4.5 V; V _D = V _S = 1 V; Test Circuit 3
DIGITAL INPUTS					
Input High Voltage, V _{INH}			2.0	V min	V _{IN} = V _{INL} or V _{INH}
Input Low Voltage, V _{INL}			0.8	V max	
Input Current I _{INL} or I _{INH}	0.001		±0.5	μA typ μA max	
DYNAMIC CHARACTERISTICS ²					
t _{ON}	7 15	20		ns typ ns max	R _L = 100 Ω, C _L = 35 pF, V _S = +3 V; Test Circuit 4
t _{OFF}	4 8	9		ns typ ns max	R _L = 100 Ω, C _L = 35 pF, V _S = +3 V; Test Circuit 4
Break-Before-Make Time Delay, t _D	5 1			ns typ ns min	R _L = 100 Ω, C _L = 35 pF, V _{S1} = V _{S2} = +5 V; Test Circuit 5
Off Isolation	–65			dB typ	R _L = 100 Ω, f = 10 MHz; Test Circuit 7
Channel-to-Channel Crosstalk	–75			dB typ	R _L = 100 Ω, f = 10 MHz; Test Circuit 8
Bandwidth –3 dB	240			MHz typ	R _L = 100 Ω; Test Circuit 6
Distortion	0.5			% typ	R _L = 100 Ω
Charge Injection	10			pC typ	C _L = 1 nF; Test Circuit 9
C _S (OFF)	10			pF typ	f = 1 kHz
C _D (OFF)	20			pF typ	f = 1 kHz
C _D , C _S (ON)	30			pF typ	f = 1 MHz
POWER REQUIREMENTS					
I _{DD}	0.001	1	1	μA max μA typ	V _{DD} = +5.5 V Digital Inputs = 0 V or V _{DD}
I _{IN}		1	1	μA typ	V _{IN} = +5 V
I _O		100		mA max	V _S /V _D = 0 V

NOTES

¹Temperature range: B Version, –40°C to +125°C.

²Guaranteed by design, not subject to production test.

Specifications subject to change without notice.

SINGLE SUPPLY ($V_{DD} = 3\text{ V} \pm 10\%$, $GND = 0\text{ V}$. All specifications T_{MIN} to T_{MAX} unless otherwise noted.)

Parameter	B Version ¹			Unit	Test Conditions/Comments
	+25°C	−40°C to +85°C	−40°C to +125°C		
ANALOG SWITCH					
Analog Signal Range	4		0 V to V _{DD}	V	V _D = 0 V to V _{DD} , I _S = −10 mA
On Resistance (R _{ON})				Ω typ	
		8	9	Ω max	
On Resistance Match between Channels (ΔR _{ON})	0.15			Ω typ	V _D = 0 V to V _{DD} , I _S = −10 mA
		0.5	0.5	Ω max	
On Resistance Flatness (R _{FLAT(ON)})	2			Ω typ	
		4	4	Ω max	V _D = 0 V to V _{DD} , I _S = −10 mA
LEAKAGE CURRENTS					
Source OFF Leakage I _S (OFF)	±0.01			nA typ	V _D = 3 V, V _S = 1 V; V _D = 1 V, V _S = 3 V; Test Circuit 2
	±0.5	±1	±1.5	nA max	
Drain OFF Leakage I _D (OFF)	±0.01			nA typ	V _D = 3 V, V _S = 1 V; V _D = 1 V, V _S = 3 V; Test Circuit 2
	±0.5	±1	±1.5	nA max	
Channel ON Leakage I _D , I _S (ON)	±0.01			nA typ	V _D = V _S = 3 V; V _D = V _S = 1 V; Test Circuit 3
	±0.5	±1	±1.5	nA max	
DIGITAL INPUTS					
Input High Voltage, V _{INH}			2.0	V min	V _{IN} = V _{INL} or V _{INH}
Input Low Voltage, V _{INL}			0.8	V max	
Input Current	0.001			μA typ	
I _{INL} or I _{INH}			±0.5	μA max	
DYNAMIC CHARACTERISTICS ²					
t _{ON}		8		ns typ	R _L = 100 Ω, C _L = 35 pF, V _S = +1.5 V; Test Circuit 4
		16	21	ns max	
t _{OFF}		5		ns typ	R _L = 100 Ω, C _L = 35 pF, V _S = +1.5 V; Test Circuit 4
		10	11	ns max	
Break-Before-Make Time Delay, t _D		5		ns typ	R _L = 100 Ω, C _L = 35 pF, V _{S1} = V _{S2} = 3 V; Test Circuit 5
		1		ns min	
Off Isolation		−65		dB typ	R _L = 50 Ω, f = 10 MHz; Test Circuit 7
Channel-to-Channel Crosstalk		−75		dB typ	
Bandwidth −3 dB		240		MHz typ	R _L = 50 Ω, f = 10 MHz; Test Circuit 8
Distortion		2		% typ	R _L = 50 Ω; Test Circuit 6
Charge Injection		3		pC typ	R _L = 50 Ω
C _S (OFF)		10		pF typ	C _L = 1 nF; Test Circuit 9
C _D (OFF)		20		pF typ	f = 1 kHz
C _D , C _S (ON)		30		pF typ	f = 1 kHz
POWER REQUIREMENTS					
					V _{DD} = +3.3 V
I _{DD}	0.001	1	1	μA max	Digital Inputs = 0 V or V _{DD}
				μA typ	
I _{IN}		1	1	μA typ	V _{IN} = +3 V
I _O		100		mA max	V _S /V _D = 0 V

NOTES

¹Temperature range: B Version, -40°C to +125°C.²Guaranteed by design, not subject to production test.

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Table I. Truth Table

$\overline{EN}$	IN	D1	D2	D3	D4	Function
1	X	Hi-Z	Hi-Z	Hi-Z	Hi-Z	DISABLE
0	0	S1A	S2A	S3A	S4A	IN = 0
0	1	S1B	S2B	S3B	S4B	IN = 1

ADG774

ABSOLUTE MAXIMUM RATINGS¹

(T_A = 25°C unless otherwise noted.)

V _{DD} to GND	−0.3 V to +6 V
Analog, Digital Inputs ²	−0.3 V to V _{DD} + 0.3 V or 30 mA, Whichever Occurs First
Continuous Current, S or D	100 mA
Peak Current, S or D	300 mA (Pulsed at 1 ms, 10% Duty Cycle max)
Operating Temperature Range	
Industrial (B Version)	−40°C to +125°C
Storage Temperature Range	−65°C to +150°C
Junction Temperature	150°C
SOIC Package, Power Dissipation	600 mW
θ _{JA} Thermal Impedance	100°C/W

QSOP Package, Power Dissipation	566 mW
θ _{JA} Thermal Impedance	149.97°C/W
Lead Temperature, Soldering (10 sec)	300°C
I R Reflow, Peak Temperature (<20 sec)	235°C
ESD	2 kV

NOTES

¹Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those listed in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Only one absolute maximum rating may be applied at any one time.

²Overvoltages at IN, S, or D will be clamped by internal diodes. Current should be limited to the maximum ratings given.

ORDERING GUIDE

Model	Temperature Range	Package Descriptions	Package Options
ADG774BR	−40°C to +125°C	Standard Small Outline Package (SOIC)	R-16
ADG774BR-REEL	−40°C to +125°C	Standard Small Outline Package (SOIC)	R-16
ADG774BR-REEL7	−40°C to +125°C	Standard Small Outline Package (SOIC)	R-16
ADG774BRZ*	−40°C to +125°C	Standard Small Outline Package (SOIC)	R-16
ADG774BRZ-REEL*	−40°C to +125°C	Standard Small Outline Package (SOIC)	R-16
ADG774BRZ-REEL7*	−40°C to +125°C	Standard Small Outline Package (SOIC)	R-16
ADG774BRQ	−40°C to +125°C	Shrink Small Outline Package (QSOP)	RQ-16
ADG774BRQ-REEL	−40°C to +125°C	Shrink Small Outline Package (QSOP)	RQ-16
ADG774BRQ-REEL7	−40°C to +125°C	Shrink Small Outline Package (QSOP)	RQ-16
ADG774BRQZ*	−40°C to +125°C	Shrink Small Outline Package (QSOP)	RQ-16
ADG774BRQZ-REEL*	−40°C to +125°C	Shrink Small Outline Package (QSOP)	RQ-16
ADG774BRQZ-REEL7*	−40°C to +125°C	Shrink Small Outline Package (QSOP)	RQ-16

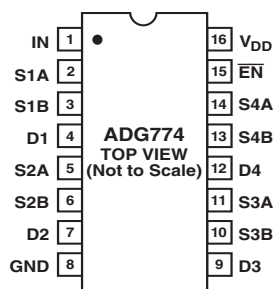
*Z = Pb-free part.

CAUTION

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the ADG774 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



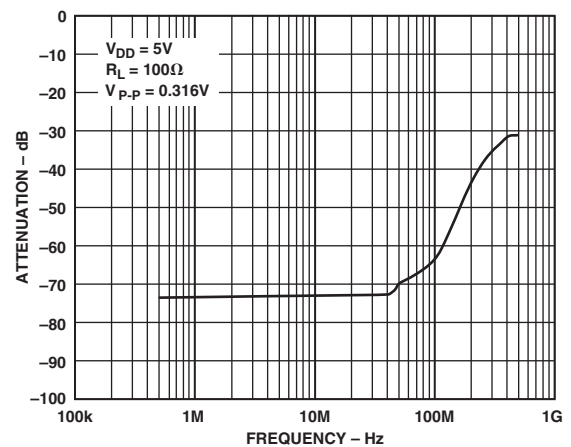
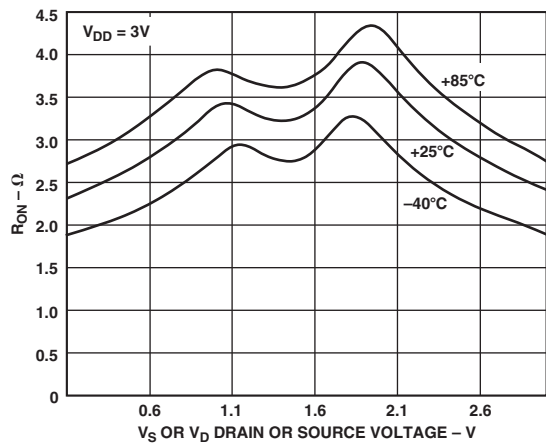
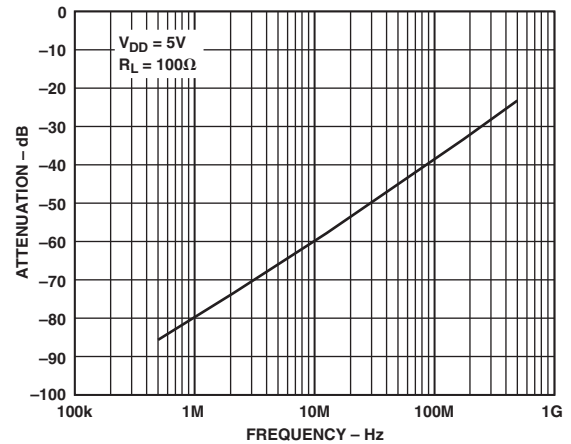
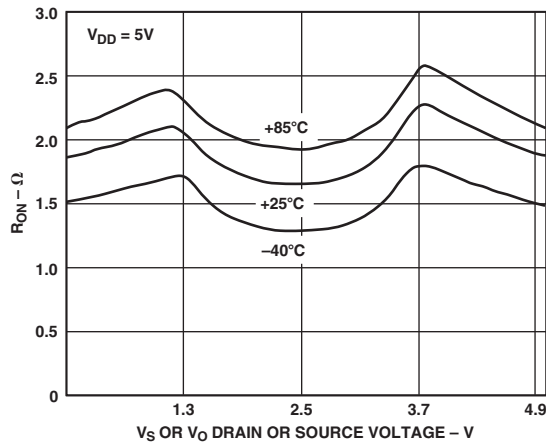
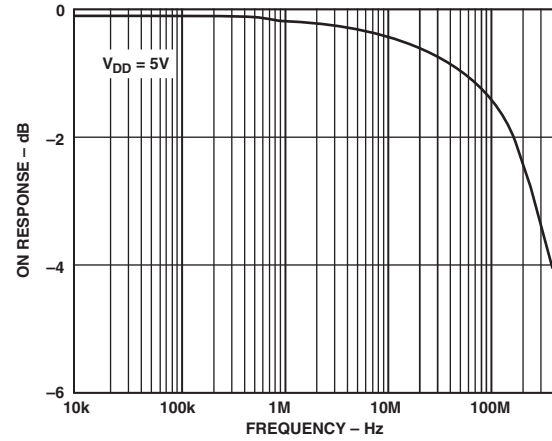
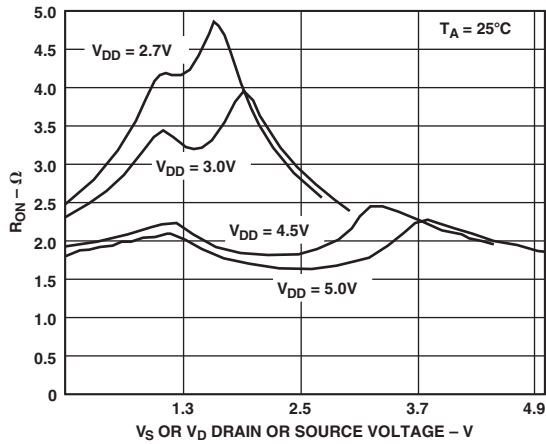
PIN CONFIGURATION (SOIC/QSOP)

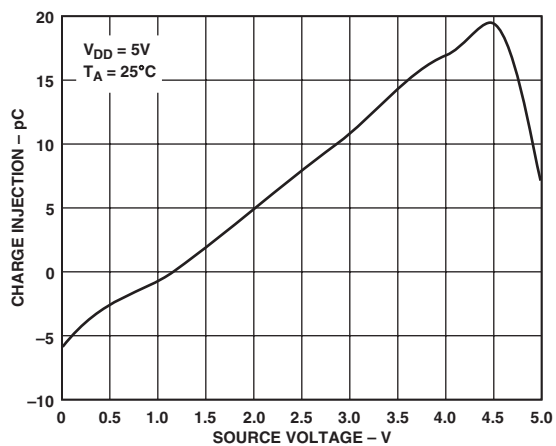


TERMINOLOGY

V_{DD}	Most Positive Power Supply Potential.
GND	Ground (0 V) Reference.
S	Source Terminal. May be an input or output.
D	Drain Terminal. May be an input or output.
IN	Logic Control Input.
$\overline{EN}$	Logic Control Input.
R_{ON}	Ohmic Resistance between D and S.
ΔR_{ON}	On Resistance Match between any Two Channels, i.e., $R_{ON\ max} - R_{ON\ min}$.
$R_{FLAT(ON)}$	Flatness is defined as the difference between the maximum and minimum value of on resistance as measured over the specified analog signal range.
I_S (OFF)	Source Leakage Current with the Switch OFF.
I_D (OFF)	Drain Leakage Current with the Switch OFF.
I_D, I_S (ON)	Channel Leakage Current with the Switch ON.
V_D (V_S)	Analog Voltage on Terminals D, S.
C_S (OFF)	OFF Switch Source Capacitance.
C_D (OFF)	OFF Switch Drain Capacitance.
C_D, C_S (ON)	ON Switch Capacitance.
t_{ON}	Delay between Applying the Digital Control Input and the Output Switching on. See Test Circuit 4.
t_{OFF}	Delay between Applying the Digital Control Input and the Output Switching Off.
t_D	OFF Time or ON Time Measured between the 90% Points of Both Switches, When Switching from One Address State to Another. See Test Circuit 5.
Crosstalk	A Measure of Unwanted Signal that is Coupled through from One Channel to Another as a Result of Parasitic Capacitance.
Off Isolation	A Measure of Unwanted Signal Coupling through an OFF Switch.
Bandwidth	Frequency Response of the Switch in the ON State Measured at 3 dB Down.
Distortion	$R_{FLAT(ON)}/R_L$

ADG774—Typical Performance Characteristics





TPC 7. Charge Injection vs. Source Voltage

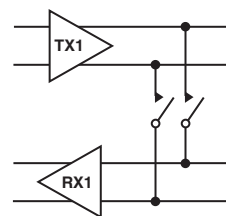


Figure 1. Loop Back

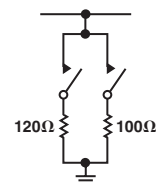


Figure 2. Line Termination

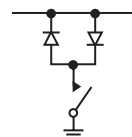
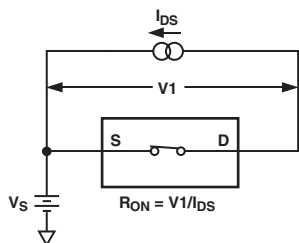


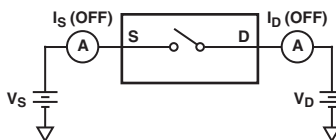
Figure 3. Line Clamp

ADG774

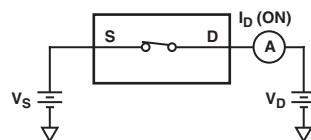
Test Circuits



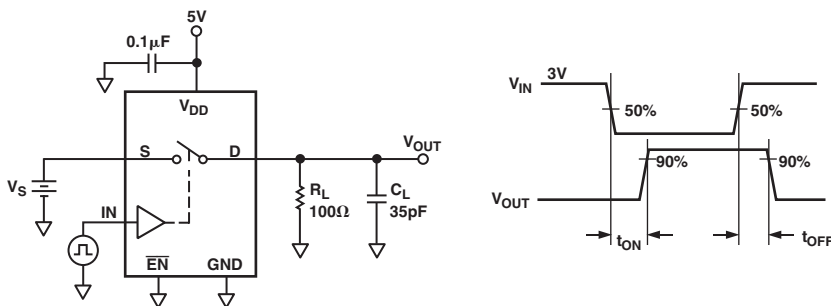
Test Circuit 1. On Resistance



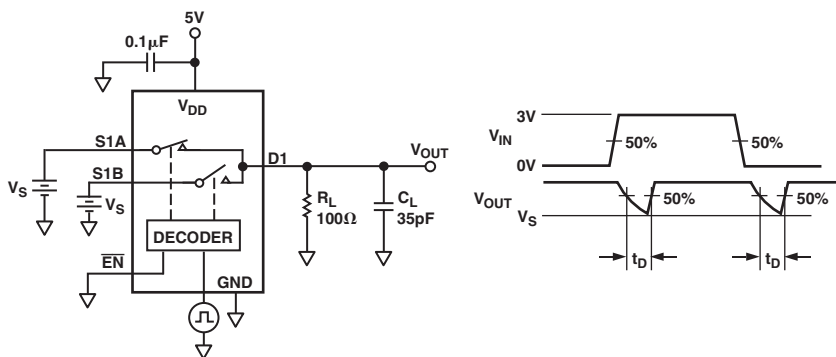
Test Circuit 2. Off Leakage



Test Circuit 3. On Leakage



Test Circuit 4. Switching Times



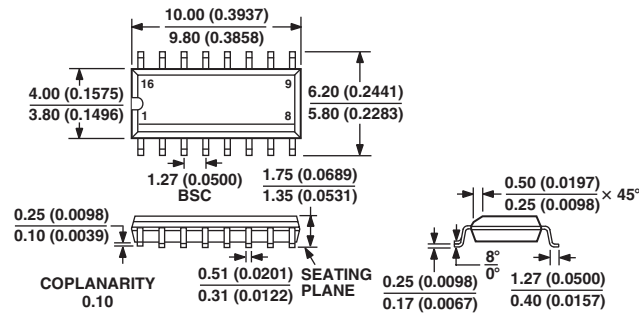
Test Circuit 5. Break-Before-Make Time Delay

Timing diagram showing V_{IN} and V_{OUT} signals. V_{IN} is a square wave with a high level of 3V. V_{OUT} is a square wave that follows V_{IN} but has a lower high level. The difference between the high levels is labeled ΔV_{OUT} . Below the V_{OUT} signal, the equation $Q_{INJ} = C_L \times \Delta V_{OUT}$ is shown, with an arrow pointing to the ΔV_{OUT} label.

OUTLINE DIMENSIONS

16-Lead Standard Small Outline Package [SOIC]
Narrow Body
(R-16)

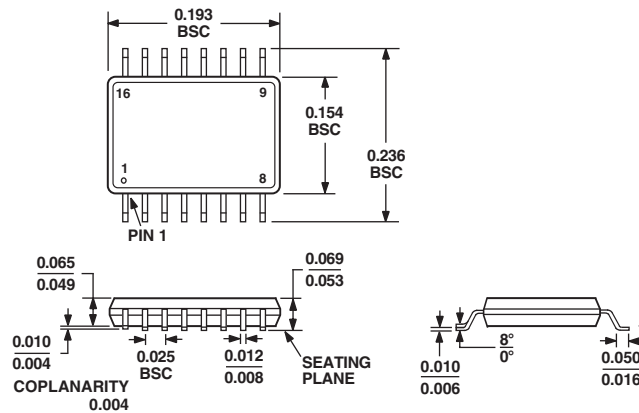
Dimensions shown in millimeters and (inches)



COMPLIANT TO JEDEC STANDARDS MS-012AC
CONTROLLING DIMENSIONS ARE IN MILLIMETERS; INCH DIMENSIONS
(IN PARENTHESES) ARE ROUNDED-OFF MILLIMETER EQUIVALENTS FOR
REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN

16-Lead Shrink Small Outline Package [QSOP]
(RQ-16)

Dimensions shown in inches



COMPLIANT TO JEDEC STANDARDS MO-137AB

Revision History

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3/04—Data Sheet changed from REV. B to REV. C.	
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Changes to ORDERING GUIDE	4
10/03—Data Sheet changed from REV. A to REV. B.	
Updated formatting	Universal
Renumbered TPCs and Figures	Universal
Changes to FEATURES	1
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Changes to ABSOLUTE MAXIMUM RATINGS	4
Updated ORDERING GUIDE	4
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4/03—Data Sheet changed from REV. 0 to REV. A.	
Renumbered TPCs and Figures	Universal
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